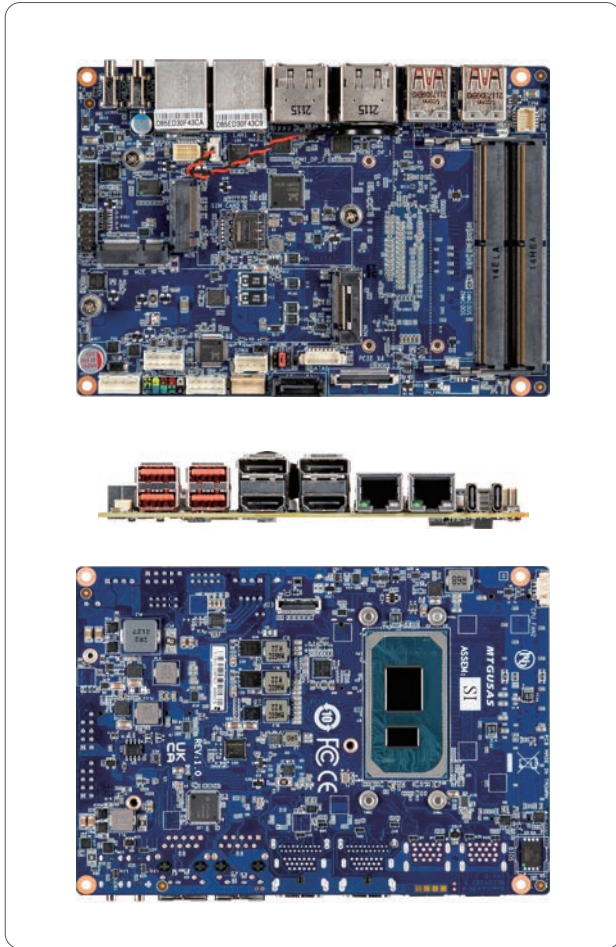


QBiP-1115G4EA (MTGU3AS)

3.5" SubCompact Board with 11th Generation Intel® Core™ i3-1115G4E Processor, Dual Channel DDR4 memory, 1 x COM, 1 x SATA 6Gb/s, 4 x USB 3.2 Type A Gen 2x1, 2 x USB 3.2 Type C Gen 2x1, 4 x USB 2.0



Features

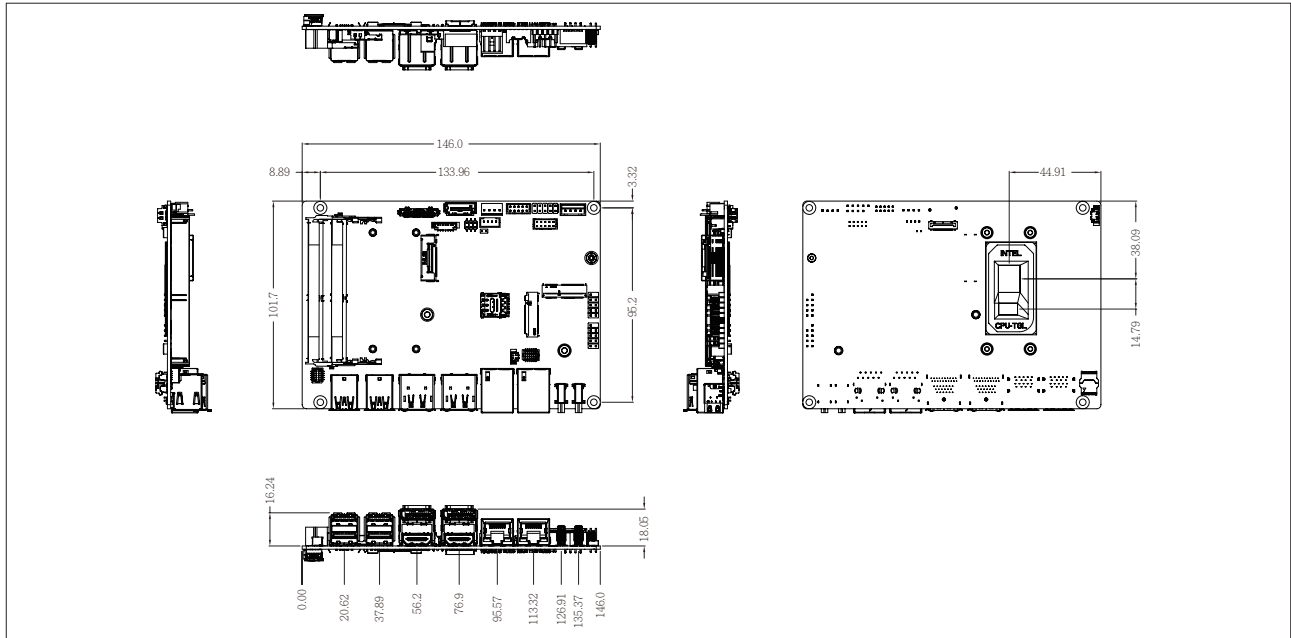
- 3.5" SBC
- Intel® Core™ i3-1115G4E Processor
- Dual Channel DDR4, 2 x SO-DIMMs
- 2 x GbE LAN ports
- 1 x SATA 6Gb/s port
- Ultra-Fast M.2 with PCIe Gen3 x2 interface
- 2 x HDMI, 2 x DP, eDP ports for multiple display
- 1 x COM Port (RS-232 and 5V/12V/RI)
- 4 x USB 3.2 Type A Gen 2x1
- 2 x USB 3.2 Type C Gen 2x1

Specifications

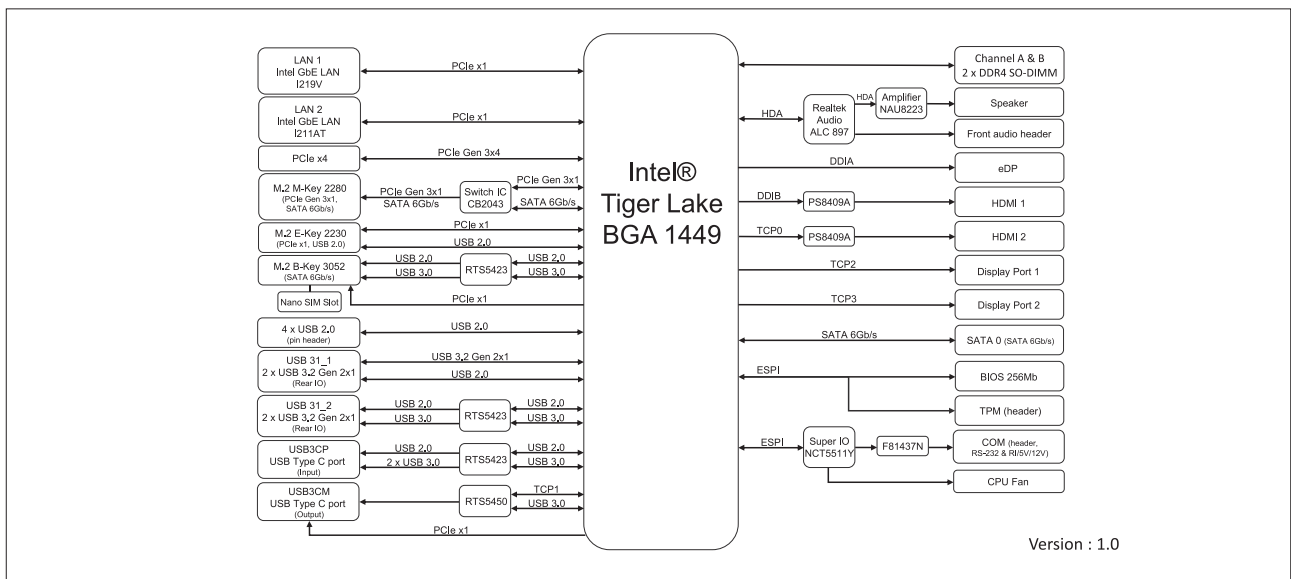
Form Factor	3.5" SBC 146W x 101.7Dmm
CPU	Intel® Core™ i3-1115G4E Processor 10nm SuperFin, 2 cores, 4 threads, up to 3.9 GHz TDP 28W 6 MB Smart Cache
Socket	1 x FCBGA1449
Chipset	—
Memory	2 x DDR4 SO-DIMM sockets, Max. Capacity 64 GB Support Dual Channel DDR4 3200MHz memory modules
Ethernet	2 x GbE LAN Ports (Intel® I219V and Intel® I211AT)
Video	Integrated Graphics Processor - Intel® Iris® Xe Graphics 2 x HDMI 2.0 port, supporting a maximum resolution of 4096x2160 @60Hz 2 x DP 1.4 ports, supporting a maximum resolution of 7680x4320 @30Hz 1 x DP 1.4 through USB type C (8k), supporting a maximum resolution of 7680x4320 @30Hz 1 x eDP port, supporting a maximum resolution of 4096x2304 @60Hz (4 independent display outputs)

Audio	Realtek® Audio Codec
Storage	1 x SATA 6Gb/s Port
Raid	Intel® SATA RAID 0/1
Expansion Slots	1 x 2280 M.2 M-Key (PCIe x2, SATA 6Gb/s) 1 x 2230 M.2 E-Key 1 x 3052 M.2 B-Key with SIM Slot (Support 5G) 1 x PCIe x4 (Board to Wire connector)
Internal I/O	1 x 4-pin box power connector (DC in +12V~24VDC) 1 x SATA Power header 1 x CPU fan header 1 x Front panel header 1 x Front panel audio header 1 x 2W Speaker out header 4 x USB 2.0 headers 1 x COM header (RS-232 & RI/5V/12V) 1 x eDP power header
Rear I/O	1 x USB type C (USB 3.2 Gen 2x1 + DP output-share with DP) & PD Out -100W 1 x USB type C (USB 3.2 Gen 2x1, PD input-100W) 4 x USB 3.2 Gen 2x1 2 x HDMI 2 x DP 2 x RJ45 LAN Ports
TPM	1 x TPM header
OS Compatibility	Windows® 10/11 (x64)
Operating Properties	Operating temperature: 0°C to 60°C Operating humidity: 0-90% (non-condensing) Non-operating temperature: -40°C to 85°C Non-operating humidity: 0%-95% (non-condensing)
Packing Content	Carton size: 465 x 351 x 217 (mm) Packing Capacity: 10pcs Single Box size: 221 x 178 x 65 (mm) Including: SATA power Cable x 1 (P/N: 25CRI-200B02-K1R)
Order Information	9MTGU3ASMR-SI (Box Packing)

GIGAIPC reserves the right to modify or change technical data without prior notice.



Block Diagram



Version : 1.0

Optional Kit

Part No.	Description	Quantity
25ST1-1Z3101-AFR	Fanless Heatsink	1
25ST4-113101-A7R	Fansink	1
25ST5-111500-YOR	Heat spreader	1
9CTM010NR-00	TPM 2.0 module	1
25CRZ-100600-S9R	TPM Cable	1